





Development of the ATLAS Liquid Argon Calorimeter Readout Electronics for the HL-LHC

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July 30th 2020 - ICHEP Conference - Virtual

HL-LHC



* Full calorimeter readout electronic chain upgraded (physical detectors kept in place)

* Why upgrading ?

- Very large pileup (~200)
- Current electronic not qualified for 4000 fb⁻¹
- Incompatibility with future ATLAS trigger scheme
- Technological progresses
- Goal: maintain and enhance physics reach during HL-LHC (per-mil linearity at EWK scale, 16-bit dynamic range, low electronic noise)
- * Installation during the 3rd long shut-down of the LHC.

The Liquid Argon Calorimeters

 Ar electromagnetic

 end-cap (E/NEC)

 Lead

 Mr electromagnetic

 barrel (EMB)

 Lead

 Copper & Tungsten

- Liquid Argon Sampling calorimeters with fine granularity
 - ✤ ~180 000 cells
- ✤ ~50 MeV to 3 TeV, ~0.8-1% constant term
- In operation since installation in 2006



LAr Phase II: upgrade of the readout electronics



Calibration system

- Inject exponential pulse of known amplitude (DAC) on the detector cell, to probe electronic response (μA)
- * Requirements:
 - Integral non-linearity (INL) <0.1% Uniformity <0.25%, 16
 bit dynamic range, Pulse rise time <1 ns
 - Radiation-tolerant to 1.8 kGy

CLAROCv2 (Calibration of Liquid ARgon Output Chip):

- Custom HF switch + DAC 16-bits in XFAB HVCMOS 180nm, 4 different channels
- Chip + test boards received in January 2020
- * Tests in laboratory test bench:
 - Excellent linearity of HF-Switch part and DAC 10-bits (0.05%)
 - 13-bits DAC (10 bits+thermometers) and 16-bits DAC (13bits + current mirrors) have larger INL (~0.4%) due to bit mismatches.





Calibration system

Switch linearity

Tests under X-ray irradiation, up to 10kGy TID

- HF switch and current mirror stable
- DAC 10 and 13-bits degraded after 0.5 kGy
 - will need to go for another technology (TSMC 130nm)

* Next steps:

- Submission of 2 ASICs by the fall
 - HF switch +mirrors in XFAB 180nm
 - DAC in TSMC 130nm with improved linearity
- First prototype of 32-channels calibration board by the end of the year





Detailed

calibration board

schematic

DAC current measured [mA]

CLAROC

(8)

Front-end: analog processing

LAUROCv2 test board

* Requirements:

- Performs pre-amplification, splitting in 2 gain scales HG and LG with ratio HG/LG of 23±5 and ENI <120-350 nA
- CR-RC² shaping of ionisation signals
- Summing of channels for L0 trigger with linearity <2%,
- ✤ Radiation tolerance up to TID =1.8 kGy.

* 2 types of ASIC under tests (CMOS TSMC 130 nm)

- LAUROCv2 (Liquid Argon Upgrade Read Out Chip)
 - Dies received in January 2020: 4 channels, 2 gains each, I²C for slow control (200 tunable parameters)
 - INL of 0.2% over 80% of dynamic range, within specification. HG/LG ratio a bit over spec, need adjustment of CR/RC² settings
 - Next steps : protons irradiation to test SEE

ALFEv1:

- 2 boards with packaged ASIC available, tests started end of June.
- Design of ALFEv1b with all features ready this summer, simulated performance within specs.
- Irradiation tests will be done





Front-end: digitization

* Requirements:

- Digitize preamplifier and shaper outputs at 40 MHz, 14-bit dynamic range and >11 bit precision
- Radiation tolerant up to 1.8 kGy

* 2 types of ASIC under tests

COLUTAv3: Full custom ASIC in TSMC 65nm, I²C interface

- 4 Dynamic Range Enhancer (DRE) + 4 Multiplying DAC (MDAC) @14bits + 12-bit pipeline Successive Approximation Register (SAR) ADC
- * Performance under study: LAr pulses with resolution within spec in almost full dynamic range, very small cross-talk
- Next step: proton irradiations for SEE testing
- ADESTO/S3-IP-Block: reuse ADC IP core developed by Adesto/S3 company for CMS ECAL, in TSMC 65 nm
 - 2nd version reviewed by CERN and Adesto/S3, submitted in May with modifications on I²C, improved power distribution, improved analog/digital separation
 - Test boards under design, dies back from foundry by end of 2020



Analog/digital separation ADESTO/S3 IP Block



Front-end board and Layer Sum Board

Front-End-Board (FEB2): final board integrating preamplifier, shaper and ADC chain, 128 channels

- Slice test board design ongoing, 32 channels, with redundant control links and different options for powering:
 - 8 LAUROCv2 +8 COLUTAv3 +8 lpGBTv1 + 2/3 VTRx
- Fabrication to start soon, tests will begin in Fall
- Full FEB2 Prototype in 2021

Layer Sum Board (LSB): sums analog readout data from preamp-shaper for L0:

- Simulation and schematics ongoing, test board this summer
- Radiation testing of op-amp will follow



Off-detector: LAr Signal Processor

- LAr Signal Processor (LASP): apply digital filtering to digitised waveforms, calculate energy and time, transmit to trigger and DAQ
 - Finalizing layout for ATCA LASP test board, routing 90% complete, ready late 2020
 - 2 processing FPGA (Stratix 10), one control FPGA (MAX10) and 12 Firefly transceiver modules
 - Mezzanine test boards for Arria10 and Stratix10 devkits (INTERMEZZO):
 - Production of 6 boards launched after production of 1 board that has been checked.
 - Firmware work well organised around git functionalities
 - First version released in June.

* SRTM (Smart Rear Transition Module)

- Complements the LASP with data monitoring, providing electro-optics and processing.
- Test cards will allow to tests all LASP/SRTM connector interfaces, soon to be submitted
- Firmware tested on devkit

SRTM firmware test on devkit

LASP routing and placement



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Off-detector: LAr Timing System

- LATOURNETT: distribution of trigger timing and control signals + configuration and monitoring of FEB2 and calibration boards.
 - Design in early stage, specification review in the fall
 - Firmware development ongoing on FPGA Cyclone10 DevKit
 - test of communication with lpGBT mezzanine test card



LATOURNETT board schematic

Summary

- * Most of the ASICs developed for the ATLAS LAr HL-LHC upgrade are in final pre-prototype stage
 - Proton irradiation testing is in most case the last step toward validation of the technology
- * Integrated board designs are starting: FEB2, calibration board, off-detector boards.
 - slice test will be done with a FEB2 pre-prototype with 1/4 channels that allows to test powering/all ASICs/data flow/communication end of 2020
- * Pandemic situation has caused a few month delays in several parts of the project
 - Especially irradiation testing have been delayed
- But still on track for an installation during 3rd long shutdown and solutions found to continue testing the devices
 - Remote access to data acquisition, test bench moved to people's homes



